



Bill of Materials  
TI DESIGNS

TIDM-TM4C129SDRAMNVM

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	9	C1, C2, C3, C4, C5, C6, C7, C8, C9	0.1uF	CAP, CERM, 0.1 $\mu$ F, 16 V, +/- 5%, X7R, 0603		C0603YC104JAT2A		0603	
2	1	C10	10 uF	CAP, CERM, 10 $\mu$ F, 6.3 V, +/- 20%, X5R, 0603		C0603C106M9PACTU		0603	
3	1	J1		Header, 100mil, 3x1, Gold, TH		TSW-103-07-G-S			
4	1	J2		Connctor, micro SD Card, 1.1 mm, R/A, SMT	Samtec	502774-0891			
5	2	P1		Connector 49 Pins Dual Row Thru Hole	Samtec	SAM1212-49-ND			
6	4	R1, R2	0 Ohms	RES, 0, 5%, 0.063 W, 0402		ERJ-2GE0R00X		0402	
7	1	R3, R4, R5, R6	19 Kohms	RES, 10.0 k, 1%, 0.063 W, 0402		CRCW040210K0FKED		0402	
8	1	U1	512 Mbit	ISSI 512Mb SDRAM	ISSI	IS42S163202D			
9	1	U2	512 Mbit	Macronix Quad SPI Serial Flash	Macronix	MX66L51235F		TSOP16	

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1	1	C1	1000pF	Capacitor, 1000pF, 2kV, 20%, X7R, 1210	Kemet	C1210C102MGRACU		1210	
2	26	C3, C4, C5, C10, C11, C12, C13, C16, C17, C18, C19, C21, C22, C23, C24, C25, C26, C27, C28, C29, C30, C40, C41, C42, C43, C46	0.1uF	Capacitor, 0.1uF 16V, 10%,0402 X7R	Taiyo Yuden	EMK105B7104KV-F		0402	
3	1	C31	4700pF	Capacitor, 4700pF, 2kV, 10%,X7R, 1812	AVX	1812GC472KAT1A		1812	
4	2	C32, C33	3300pF	Capacitor, 3300pF, 50V, 10%, X7R, 0603	TDK	C1608X7R1H332K		0603	
5	2	C6, C14	1uF	Capacitor, 1uF , X5R, 10V, Low ESR, 0402	Johanson Dielectrics Inc	100R07X105KV4T		0402	
6	3	C7, C15, C20	2.2uF	Capacitor, 2.2uF, 16V, 10%, 0603, X5R	Murata	GRM188R61C225KE15D		0603	
7	6	C8, C9, C44, C45, C47, C48	12pF	Capacitor, 12pF, 50V, 5%, 0402, COG	Murata	GRM1555C1H120JZ01D		0402	
8	5	D0, D1, D2, D3, D4		Green LED 0603	Everlight	19-217/G7C-AL1M2B/3T		0603	
9	7	J1, J2, J3, J4, J5, J6, J7		Jumper, 0.100, Gold, Black, Open	3M	969102-0000-DA			
10	1	JP1		Header, 2x3, 0.100, T-Hole, Vertical Unshrouded, 0.230 Mate, gold	FCI	67996-206HLF			
11	2	JP2, JP3		Header, 1x2, 0.100, T-Hole, Vertical Unshrouded, 0.220 Mate	FCI	68001-102HLF			
12	2	JP4, JP5		Header, 2x2, 0.100, T-Hole, Vertical Unshrouded, 0.230 Mate	FCI	67997-104HLF			
13	8	R1, R2, R3, R4, R5, R29, R35, R44	10 KOhm	Resistor, 10k ohm, 1/10W, 5%, 0402 Thick Film	Yageo	RC0402FR-0710KL		0402	
14	3	R17, R26, R36	100 KOhm	100k 5% 0402 resistor smd	Rohm	MCR01MRTJ104		0402	
15	2	R18, R51	100 Ohm	Resistor 0402 100 ohm 5%	Rohm	MCR1MRTJ101		0402	
16	4	R23, R21, R22, R24	49.9 Ohm	Resistor 49.9 ohm 0402. 1 %	Rohm	MCR01MRTF49R9		0402	
17	1	R25	4.87 Kohm	Resistor 4.87k 1% 0402 smd	Rohm	MCR01MRTF4871		0402	
18	1	R28	5.6 Kohm	Resistor, 5.6k ohm, 1/10W, 5%, 0402	Panasonic	ERJ-2GEJ562X		0402	
19	4	R32, R43, R45, R46	75 Ohm	resistor 75 ohm 0402 5%	Rohm	MCR01MRTJ750		0402	
20	2	R34, R52	1 MOhm	Resistor, 1M OH, 1/10W, 5% 0603 SMD	Panasonic	ERJ-3GEYJ105V		0603	
21	1	R38	51 Ohm	Resistor, 51 ohm, 1/10W, 5%, 0402	Panasonic	ERJ-2GEJ510X		0402	
22	1	R42	1 MOhm	Resistor, 1M ohm, 1/10W, 5%, 0402	Rohm	MCR01MRTF1004		0402	
23	1	R47	1 MOhm	RES 1M OHM 5% 1206 TF	Panasonic	ERJ-8GEYJ105V		1206	
24	2	R49, R50	2 Kohm	Resistor, 2.0k ohm, 1/10W, 5%, 0402	Panasonic	ERJ-3GEYJ202V		0402	

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25	12	R6, R7, R8, R10, R11, R15, R16, R19, R20, R39, R40, R41	0 Ohm	Resistor, 0 ohm, 1/10W, 5%, 0402	Panasonic	ERJ-2GE0R00X		0402	
26	5	R9, R27, R30, R31, R33	330 Ohm	Resistor, 330 ohm, 1/10W, 5%, 0402	Yageo	RC0402FR-07330RL		0402	
27	4	RESET, USR_SW1, USR_SW2, WAKE		Switch, Tact 6mm SMT, 160gf	Omron	B3S-1000			
28	1	U1		Tiva, MCU TM4C1294NCPDT 128 QFP with Ethernet MAC + PHY	Texas Instruments	TM4C1294NCPDT			TQFP-128
29	1	U10		Transformer, ethernet, 1 to 1. SOIC 16	Pulse Electronics	HX1198FNL			SOIC-16
30	1	U13		Diode, 8 chan, +/-15KV, ESD Protection Array, SO-8	Semtech	SLVU2.8-4.TBT			SO-8
31	1	U14		Connector, RJ45 NO MAG, shielded THRU HOLE	TE Connectivity	1-406541-5			
32	2	U2, U3		IC 4CH ESD SOLUTION, W/CLAMP 6SON	Texas Instruments	TPD4S012DRYR			
33	1	U20		TIVA MCU TM4C123GH6PMI	Texas Instruments	TM4C123GH6PMI			QFP-64
34	1	U22		USB Micro B receptacle right angle with guides	FCI	10118194-0001LF			
35	1	U4		Fault protected power switch, dual channel, 8-SON	Texas Instruments	TPS2052BDRBR			
36	1	U5		3.3V LDO TI TPS73733DRV fixed out 5V in	Texas Instruments	TPS73733DRV			
37	1	U6		Header 2x5, 0.050, SM, Vertical Shrouded	Samtec	SHF-105-01-S-D-SM			
38	1	U7		USB Micro AB receptacle. Right angle with through guides	Hirose	ZX62D-AB-5P8			
39	4	X6, X7, X8, X9		Header, 2x10, T-Hole Vertical unshrouded stacking	Samtec	SSW-110-23-S-D			
40	1	Y1	25 MHz	Crystal 25 MHz 3.2 x 2.5 mm	NDK	NX3225GA-25.000M-STD-CRG-2			
41	1	Y2	16 MHz	Crystal 16 MHz 3.2 x 2.5 mm 4 pin	NDK	NX3225GA-16.000M-STD-CRG-2			
42	1	Y3	32768 Hz	Crystal, 32.768 KHz Radial Can	Citizen Finetech Miyota	CMR200T-32.768KDZY-UT			
PCB Do Not Populate List (Shown for Information only)									
43	1	C2	0.1uF	Capacitor, 0.1uF 16V, 10%, 0402 X7R	Taiyo Yuden	EMK105B7104KV-F		0402	
44	3	H1, H4, H6		Screw, #4 x 0.625" Pan Head, Sheet Metal, Phillips/Slotted (for fan)	McMaster	90077A112			
45	3	R12, R12, R14	5.6 KOhm	Resistor, 5.6k ohm, 1/10W, 5%, 0402	Panasonic	ERJ-2GEJ562X		0402	
46	1	R48	52.3 KOhm	Resistor 0402 1% 52.3k	Rohm	TRR01M2PF5232		0402	
47	17	TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP13, TP14, TP15, TP16, TP17		Terminal, Test Point Miniature Loop, Red, T-Hole	Keystone	5000			
48	1	X1		Header, 2x7, 0.100, T-Hole, Vertical, Unshrouded, 0.230 Mate	FCI	67997-114HLF			
49	1	X11A		Valvano style bread board connect. Right Angle extended, 1 x 49 0.100 pitch.	Samtec	TSW-149-09-F-S-RE			
50	1	X11B		valvano style breadboard header.	Samtec	TSW-149-08-F-S-RA			

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